

LOW NOISE, J-FET INPUT OPERATIONAL AMPLIFIERS

FEATURES

• Wide Power Supply Range	± 4 to $\pm 18V$
• Internal ESD Protection	Human Body Model (HBM) $\pm 2000V$ typ.
• High Input Resistance	$10^{12}\Omega$ typ.
• Wide Temperature Range	-40°C to 125°C
• Bipolar Technology	
• High Slew Rate	13V/ μ s typ.
• Wide Unity Gain Bandwidth	3MHz typ.
• Package	
NJM072C/072CA/082C/082CA	SOP8
NJM072C/072CA/082C/082CA	SSOP8
NJM074C/074CA/084C/084CA	SOP14
NJM074C/074CA/084C/084CA	SSOP14

DESCRIPTION

The NJM072C/082C/NJM074C/084C are JFET input operational amplifiers. They feature low input bias and offset currents, high input impedance and fast slew rate.

The low harmonic distortion and low noise make them ideally suit for amplifiers with high fidelity and audio amplifier applications.

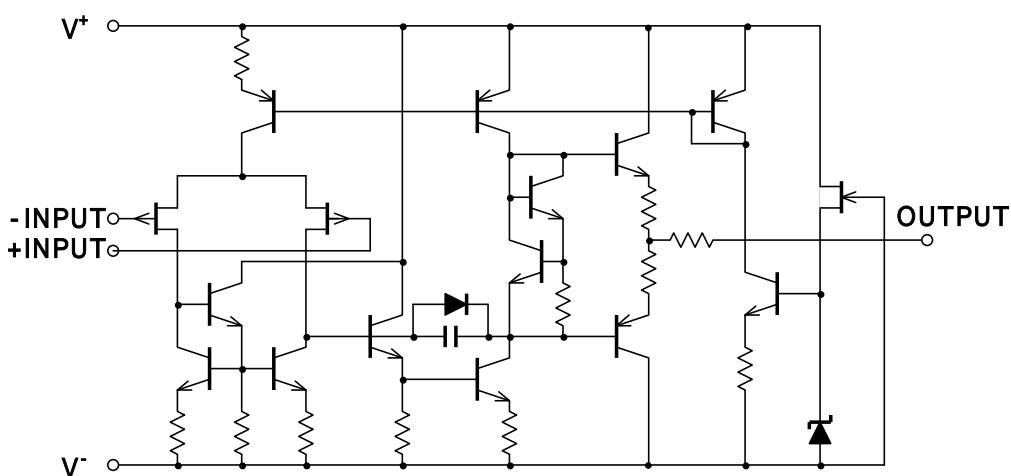
In addition, the realization of a wide operating temperature reaches by a new design.

Product Name	Dual Quad	NJM072CG/CV	NJM082CG/CV	NJM072CAG/CAV	NJM082CAG/CAV
Input Offset Voltage		10mV max.	15mV max.		6mV max.

APPLICATIONS

- Industrial Measuring Instruments
- Active Filters
- Sensor Amplifiers
- Audio Amplifiers / Filters
- Photodiode Amplifiers

■ EQUIVALENT CIRCUIT



■ PIN CONFIGURATIONS

PRODUCT NAME	NJM072CG/CAG	NJM082CG/CAG	NJM072CV/CAV	NJM082CV/CAV
Package	SOP8		SSOP8	
Pin Functions	<p>(Top View)</p> <p>A OUTPUT 1 A -INPUT 2 A +INPUT 3 V- 4 B +INPUT 5 B -INPUT 6 B OUTPUT 7 V+ 8</p> <p>B +INPUT 5 B -INPUT 6 B OUTPUT 7 V- 4 A +INPUT 3 A -INPUT 2 A OUTPUT 1 V+ 8</p>		<p>(Top View)</p> <p>A OUTPUT 1 A -INPUT 2 A +INPUT 3 V- 4 B +INPUT 5 B -INPUT 6 B OUTPUT 7 V+ 8 B +INPUT 5 B -INPUT 6 B OUTPUT 7 V- 4 A +INPUT 3 A -INPUT 2 A OUTPUT 1 V+ 8</p>	
PRODUCT NAME	NJM074CG/CAG	NJM084CG/CAG	NJM074CV/CAV	NJM084CV/CAV
Package	SOP14		SSOP14	
Pin Functions	<p>(Top View)</p> <p>A OUTPUT 1 A -INPUT 2 A +INPUT 3 V+ 4 B +INPUT 5 B -INPUT 6 B OUTPUT 7 D OUTPUT 14 D -INPUT 13 D +INPUT 12 V- 11 C +INPUT 10 C -INPUT 9 C OUTPUT 8</p>		<p>(Top View)</p> <p>A OUTPUT 1 A -INPUT 2 A +INPUT 3 V+ 4 B +INPUT 5 B -INPUT 6 B OUTPUT 7 D OUTPUT 14 D -INPUT 13 D +INPUT 12 V- 11 C +INPUT 10 C -INPUT 9 C OUTPUT 8</p>	

■ PRODUCT NAME INFORMATION

NJM072C G (TE2)
 Part Number Package Taping Form

■ ORDER INFORMATION

PRODUCT NAME	PACKAGE	RoHS	HALOGEN-FREE	TERMINAL FINISH	MARKING	WEIGHT (mg)	MOQ (pcs)
NJM072CG (TE2)	SOP8	Yes	Yes	Pure Sn	072	88	2500
NJM072CAG (TE2)	SOP8	Yes	Yes	Pure Sn	072A	88	2500
NJM082CG (TE2)	SOP8	Yes	Yes	Pure Sn	082	88	2500
NJM082CAG (TE2)	SOP8	Yes	Yes	Pure Sn	082A	88	2500
NJM072CV (TE1)	SSOP8	Yes	Yes	Sn2Bi	072	42	2000
NJM072CAV (TE1)	SSOP8	Yes	Yes	Sn2Bi	072A	42	2000
NJM082CV (TE1)	SSOP8	Yes	Yes	Sn2Bi	082	42	2000
NJM082CAV (TE1)	SSOP8	Yes	Yes	Sn2Bi	082A	42	2000
NJM074CG (TE2)	SOP14	Yes	Yes	Pure Sn	074	150	2500
NJM074CAG (TE2)	SOP14	Yes	Yes	Pure Sn	074A	150	2500
NJM084CG (TE2)	SOP14	Yes	Yes	Pure Sn	084	150	2500
NJM084CAG (TE2)	SOP14	Yes	Yes	Pure Sn	084A	150	2500
NJM074CV (TE1)	SSOP14	Yes	Yes	Sn2Bi	074	65	2000
NJM074CAV (TE1)	SSOP14	Yes	Yes	Sn2Bi	074A	65	2000
NJM084CV (TE1)	SSOP14	Yes	Yes	Sn2Bi	084	65	2000
NJM084CAV (TE1)	SSOP14	Yes	Yes	Sn2Bi	084A	65	2000

■ ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT
Supply Voltage	V ⁺ /V ⁻	±18	V
Differential Input Voltage ⁽¹⁾	V _{ID}	±36	V
Input Voltage ⁽²⁾	V _{IN}	V-0.3 to V+36	V
Output Terminal Input Voltage	V _O	V-0.3 to V ⁺ +0.3	V
Power Dissipation (Ta=25°C) ⁽³⁾	P _D	2-Layer / 4-Layer ⁽⁴⁾ 720 / 1100 460 / 570 1000 / 1500 560 / 700	mW
Storage Temperature	T _{stg}	-65 to 150	°C
Junction Temperature	T _j	150	°C

■ THERMAL CHARACTERISTICS

PACKAGE	SYMBOL	VALUE	UNIT
Junction-to-Ambient Thermal Resistance		2-Layer / 4-Layer ⁽⁴⁾ 175 / 118 274 / 218 121 / 81 224 / 178	°C/W
SOP8 SSOP8 SOP14 SSOP14	Θ _{ja}		
Junction-to-Top of Package Characterization Parameter		2-Layer / 4-Layer ⁽⁴⁾ 42 / 37 39 / 38 23 / 18 40 / 36	°C/W
SOP8 SSOP8 SOP14 SSOP14	Ψ _{jt}		

(1) Differential voltage is the voltage difference between +INPUT and -INPUT.

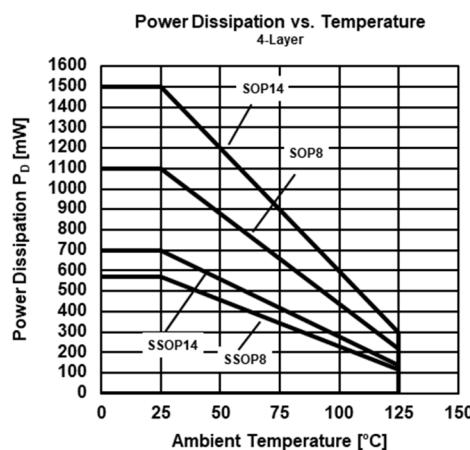
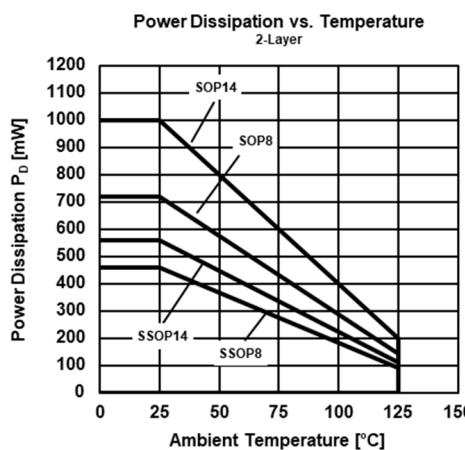
(2) Input voltage is the voltage should be allowed to apply to the input terminal independent of the magnitude of V⁺.

The normal operation will establish when any input is within the "Common-Mode Input Voltage Range" of electrical characteristics.

(3) Power dissipation is the power that can be consumed by the IC at Ta=25°C, and is the typical measured value based on JEDEC condition.

(4) 2-Layer: Mounted on glass epoxy board. (76.2x114.3x1.6 mm: based on EIA/JDEC standard, 2-layer FR-4)

4-Layer: Mounted on glass epoxy board. (76.2x114.3x1.6 mm: based on EIA/JDEC standard, 4-layer FR-4), internal Cu area: 74.2 x 74.2 mm

■ POWER DISSIPATION vs. AMBIENT TEMPERATURE

■ RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	CONDITIONS	VALUE	UNIT
Supply Voltage	V ⁺ /V ⁻	T _a = 25°C	±4 to ±18	V
Operating Temperature	T _{opr}		-40 to 125	°C



NJM072C/074C NJM072CA/074CA

NJM082C/084C NJM082CA/084CA

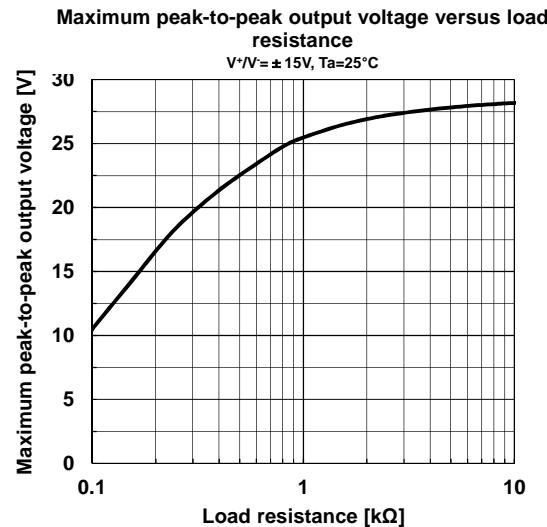
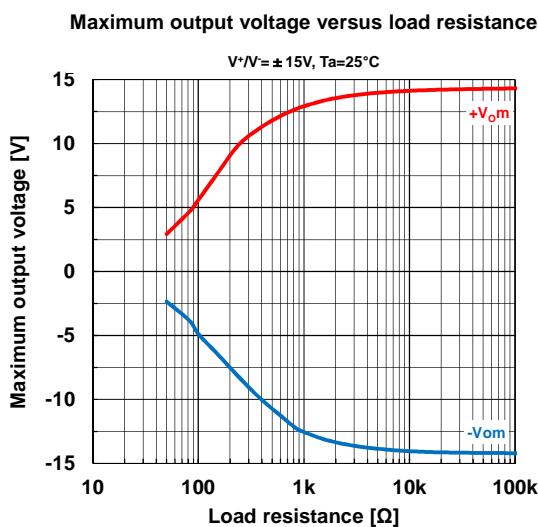
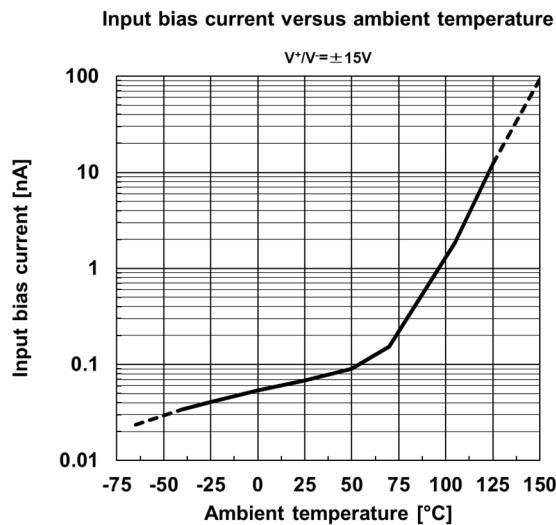
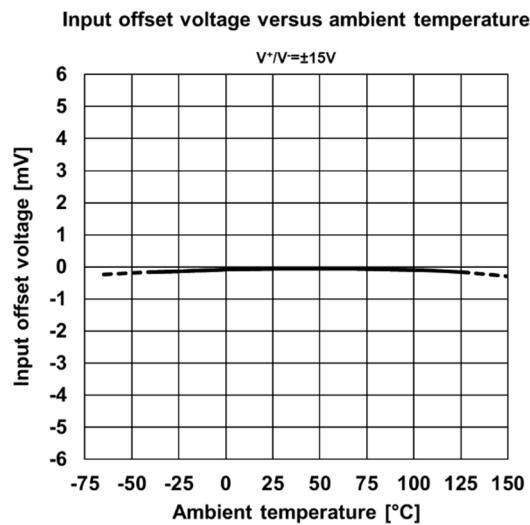
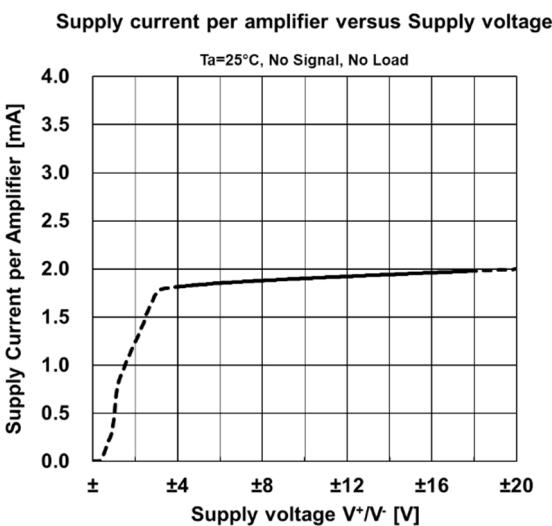
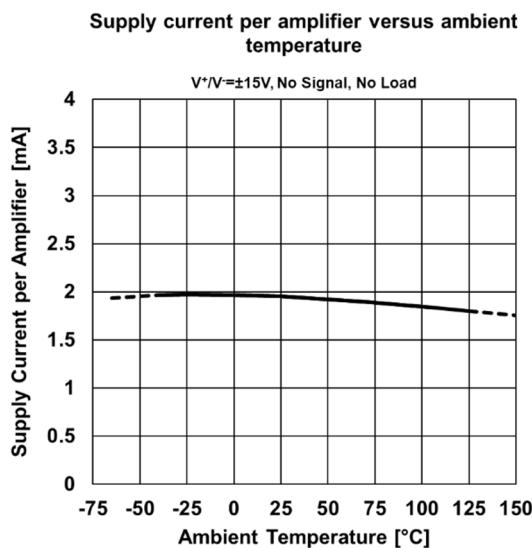
ELECTRICAL CHARACTERISTICS

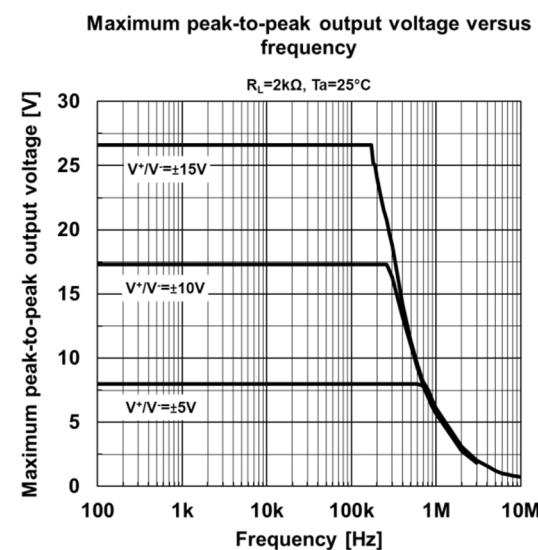
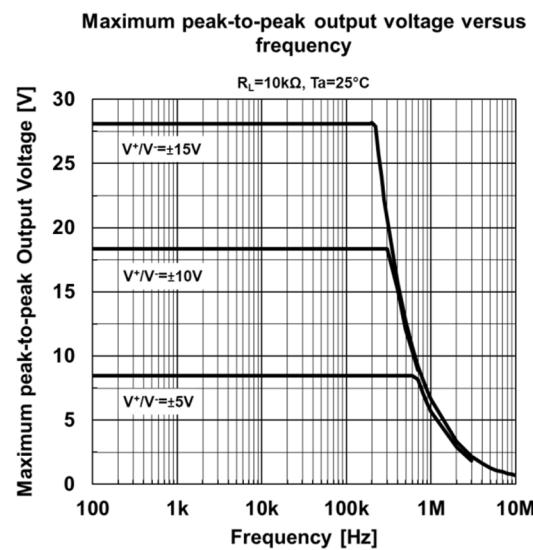
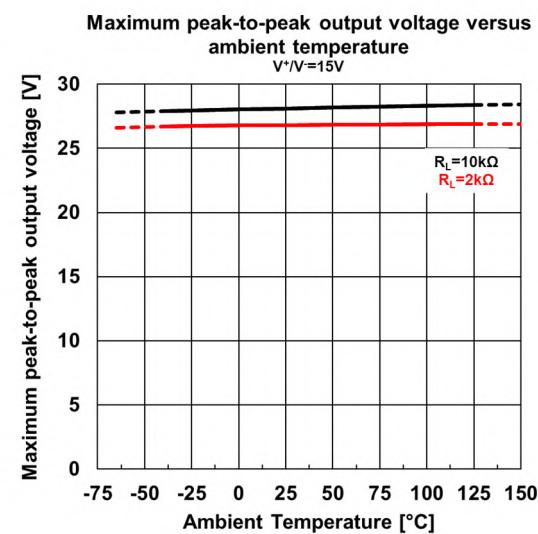
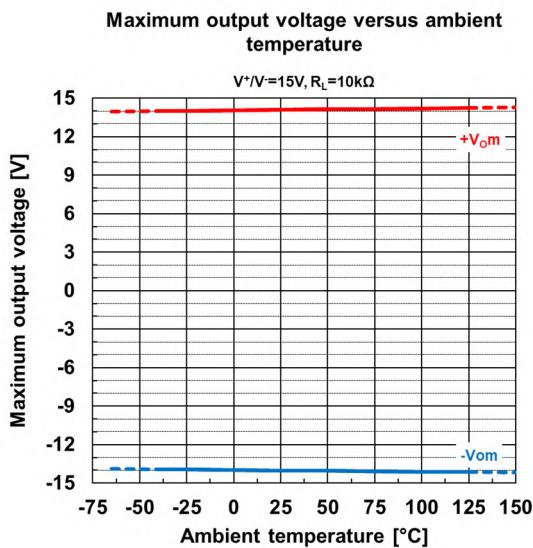
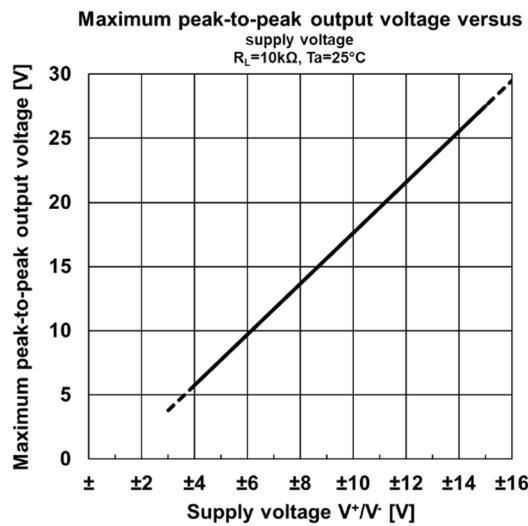
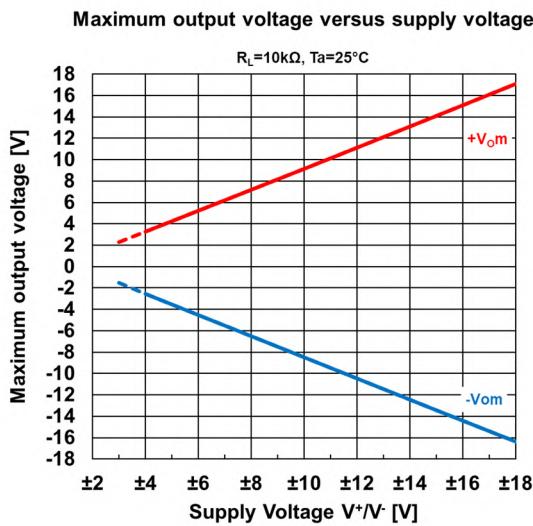
(V⁺/V⁻ = ± 15V, Ta = 25°C, unless otherwise noted.)

() Applies to NJM082C and NJM084C

PARAMETER	SYMBOL	TEST CONDITIONS	NJM072C / NJM082C NJM074C / NJM084C			NJM072CA / NJM082CA NJM074CA / NJM084CA			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
INPUT CHARACTERISTICS									
Input Offset Voltage	V _{IO}	R _S =50Ω, Ta = 25°C R _S =50Ω, 0°C < Ta < 70°C ⁽⁵⁾	-	3	10(15) 13(15)	-	3	6(6) 7(7.5)	mV
Input Offset Voltage Drift	ΔV _{IO} /ΔT	R _S =50Ω, 0°C < Ta < 70°C ⁽⁵⁾	-	18	-	-	18	-	μV/°C
Input Bias Current	I _B	Ta = 25°C 0°C < Ta < 70°C ⁽⁵⁾	-	30	200(400) 7	-	30	200 7	pA nA
Input Offset Current	I _{IO}	Ta = 25°C 0°C < Ta < 70°C ⁽⁵⁾	-	5	50(200) 10	-	5	50(100) 2	pA nA
Input Resistance	R _{IN}		-	10 ¹²	-	←	←	←	Ω
Open-Loop Voltage Gain	A _V	R _L ≥2kΩ, V _O =±10V, Ta = 25°C R _L ≥2kΩ, V _O =±10V, 0°C < Ta < 70°C ⁽⁵⁾	25 15	200 -	-	50 25	200 -	-	V/mV
Common-Mode Rejection Ratio	CMR	V _{IC} =V _{ICM} MIN, R _S ≤10kΩ	70	100	-	75	100	-	dB
Common-Mode Input Voltage Range	V _{ICM}	≥ CMR MIN	±11	-12 to 15	-	←	←	←	V
OUTPUT CHARACTERISTICS									
Maximum Output Voltage	V _{OM}	R _L =10kΩ R _L =10kΩ, 0°C < Ta < 70°C ⁽⁵⁾ R _L =2kΩ, 0°C < Ta < 70°C ⁽⁵⁾	±12 ±12 ±10	±13.5 - -	-	← ← ←	← ← ←	←	V
POWER SUPPLY									
Supply Current per Amplifier	I _{SUPPLY}	No Signal	-	1.4	2.5(2.8)	←	←	←	mA
Supply Voltage Rejection Ratio	SVR	V ⁺ /V ⁻ = ±9V to ±15V, R _S ≤10kΩ	70	100	-	80	100	-	dB
AC CHARACTERISTICS									
Slew Rate	SR	V _{IN} =10Vpp, R _L =2kΩ, C _L =00pF, See Figure1	8	13	-	←	←	←	V/μs
Unity Gain Frequency	f _T		-	3	-	←	←	←	MHz
Rise Time	t _r	V _{IN} =20mVpp , R _L =2kΩ, C _L =100pF, See Figure1	-	0.1	-	←	←	←	μs
Overshoot	K _{OV}	V _{IN} =20mVpp , R _L =2kΩ, C _L =100pF, See Figure1	-	20	-	←	←	←	%
Total Harmonic Distortion + Noise	THD+N	V _{IN} =6Vrms , G _V =0dB R _L =2kΩ, R _S =1kΩ, f = 1kHz	-	0.003	-	←	←	←	%
Equivalent Input Noise Voltage	V _{NI}	R _S =20Ω, f=10Hz to 10kHz	-	4	-	←	←	←	μVrms
	e _n	R _S =20Ω, f = 1kHz	-	18	-	←	←	←	nV/√Hz
Equivalent Input Noise Current	i _n	R _S =20Ω, f = 1kHz	-	0.01	-	←	←	←	pA/√Hz
Channel Separation	CS	G _V =40dB	-	120	-	←	←	←	dB

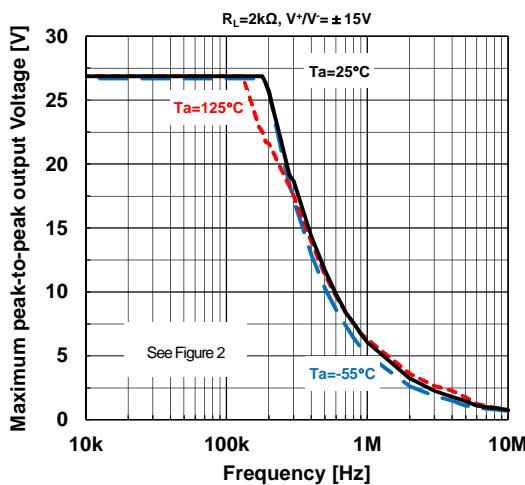
(5) This parameter is not 100% test.

■ TYPICAL CHARACTERISTICS


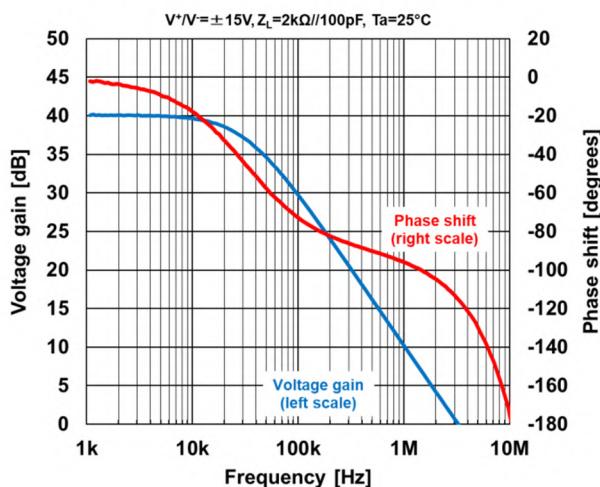
■ TYPICAL CHARACTERISTICS


■ TYPICAL CHARACTERISTICS

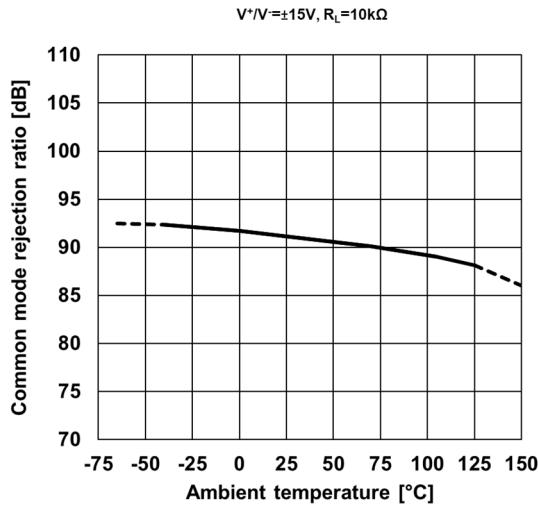
Maximum peak-to-peak output voltage versus frequency



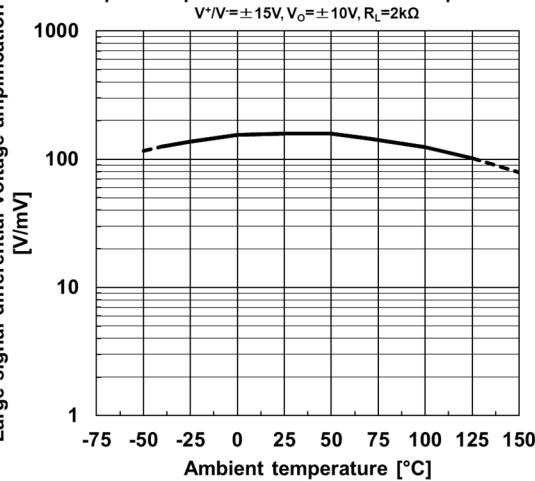
Voltage gain and phase shift versus frequency



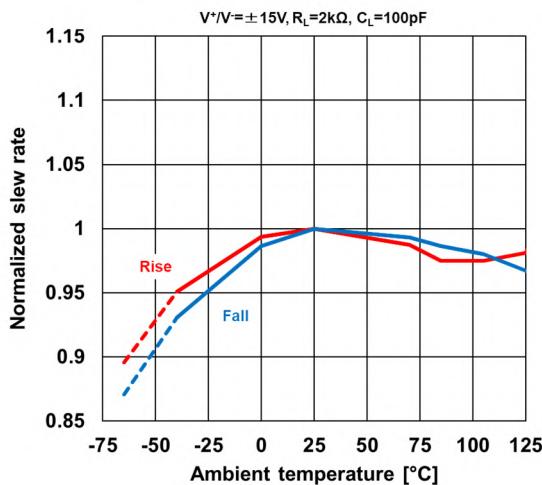
Common mode rejection ratio versus ambient temperature



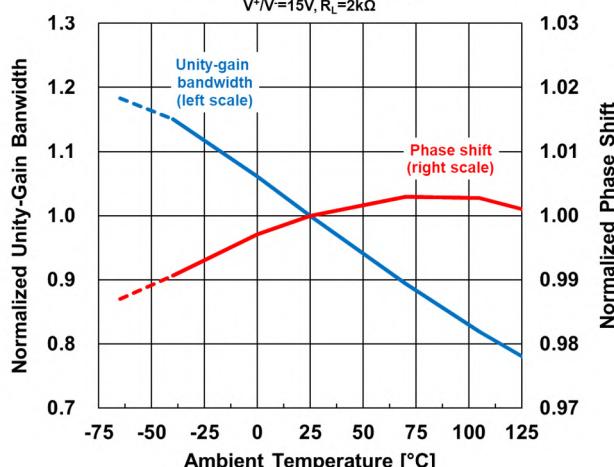
Open Loop Gain versus ambient temperature

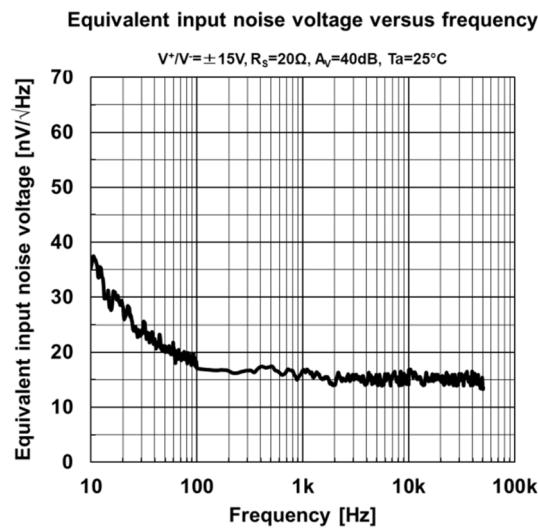
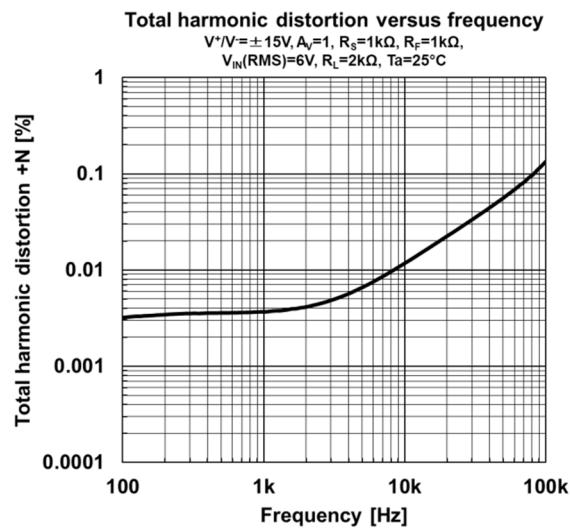
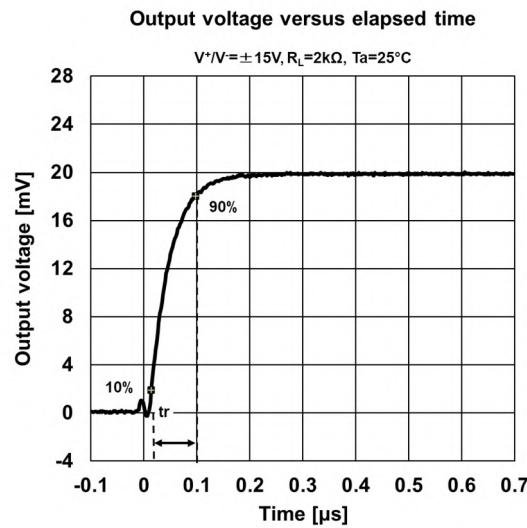
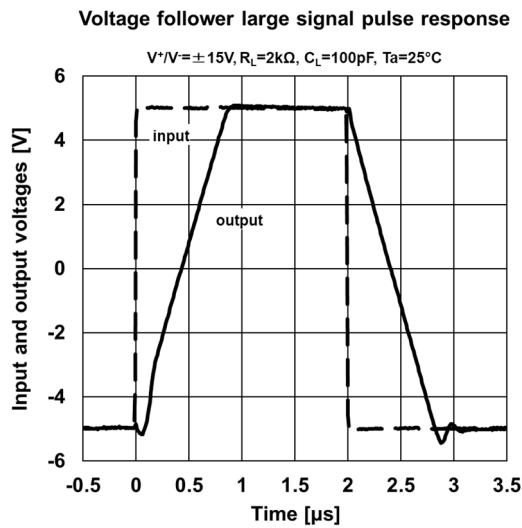


Normalized slew rate versus ambient temperature



Normalized unity-gain bandwidth and phase shift versus ambient temperature



■ TYPICAL CHARACTERISTICS


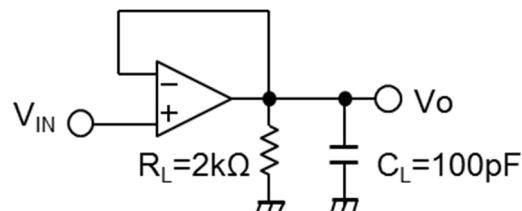
■ TEST CIRCUITS

Figure1. Voltage Follower

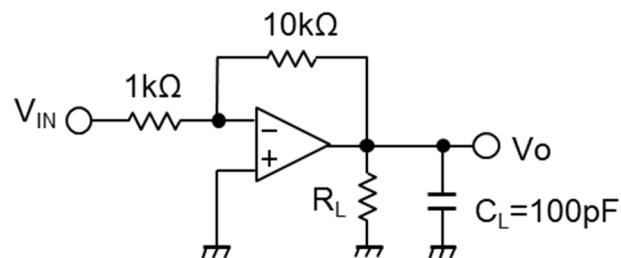
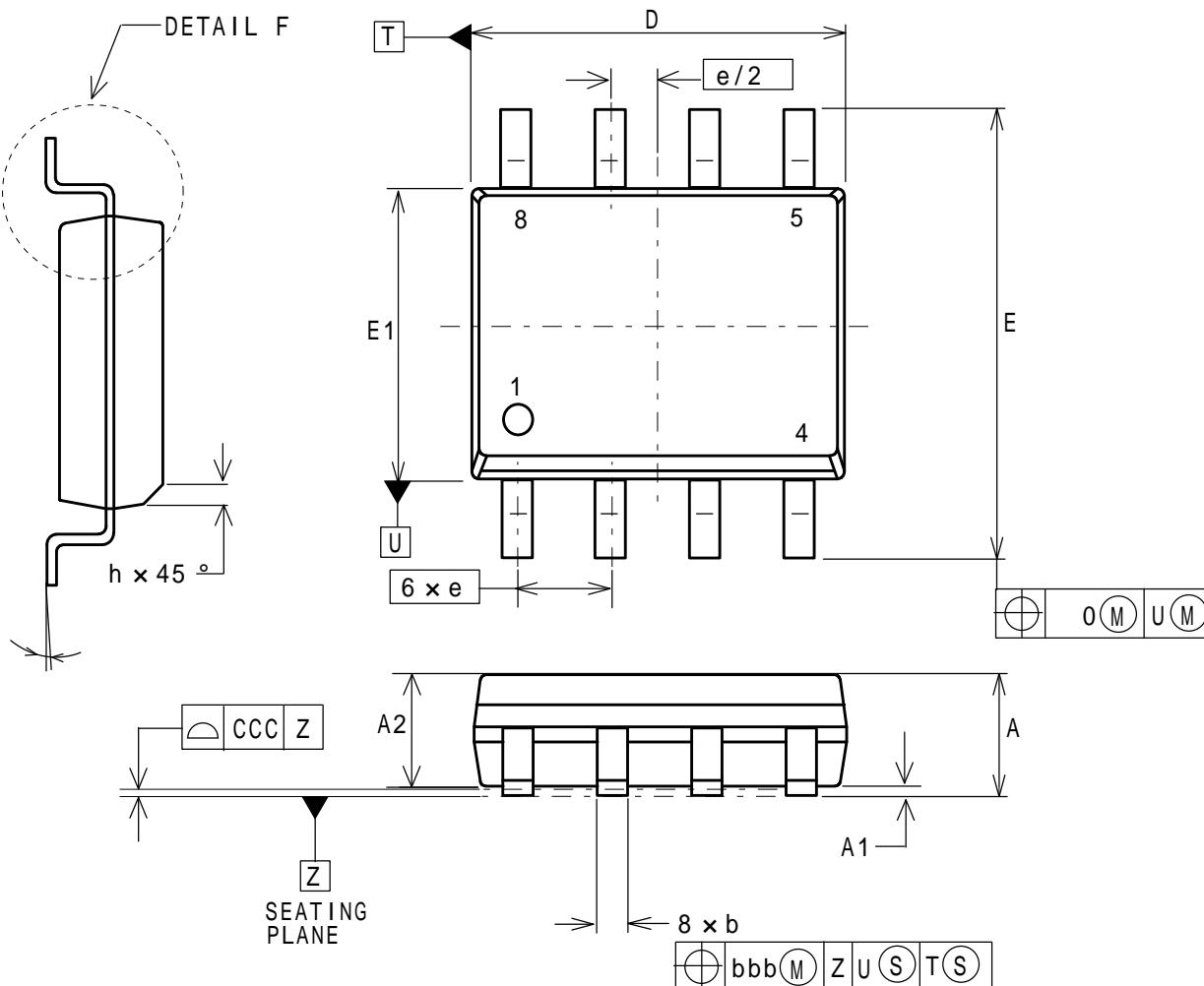


Figure2. 20dB Inverting Amplifier (*)

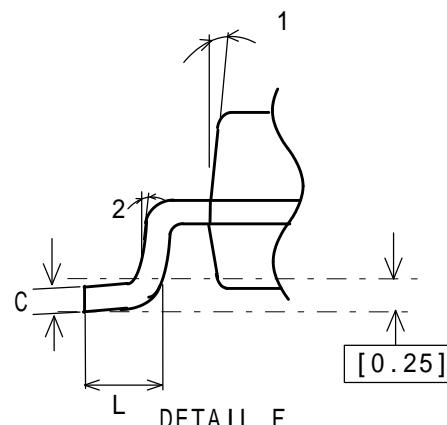
(*) 20dB Inverting Amplifier uses a Maximum Output Voltage vs. Frequency on page 6 and 7.

SOP8
■ PACKAGE DIMENSIONS

Unit: mm

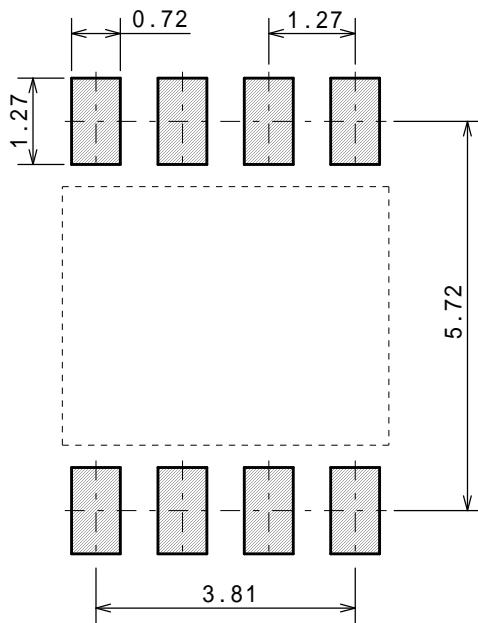


DESCRIPTION	SYMBOL	INCH			MILLIMETER		
		MIN	NCM	MAX	MIN	NCM	MAX
TOTAL THICKNESS	A	.053		.069	1.35		1.75
STAND OFF	A1	.004		.010	0.10		0.25
MOLD THICKNESS	A2	.049		-	1.25		-
LEAD WIDTH	b	.014		.019	0.35		0.49
L/F THICKNESS	c	.007		.010	0.19		0.25
BODY SIZE	D	.189		.197	4.80		5.00
	E1	.150		.157	3.80		4.00
	E	.228		.244	5.80		6.20
LEAD PITCH	e	.050	BSC		1.27	BSC	
	L	.015		.049	0.40		1.25
	h	.010		.020	0.25		0.50
	1	0°		7°	0°		7°
	2	5°		15°	5°		15°
		2°		12°	2°	7°	12°
LEAD EDGE OFFSET	0		.010		0.25		
LEAD OFFSET	bbb		.010		0.25		
COPLANARITY	CCC		.004		0.10		



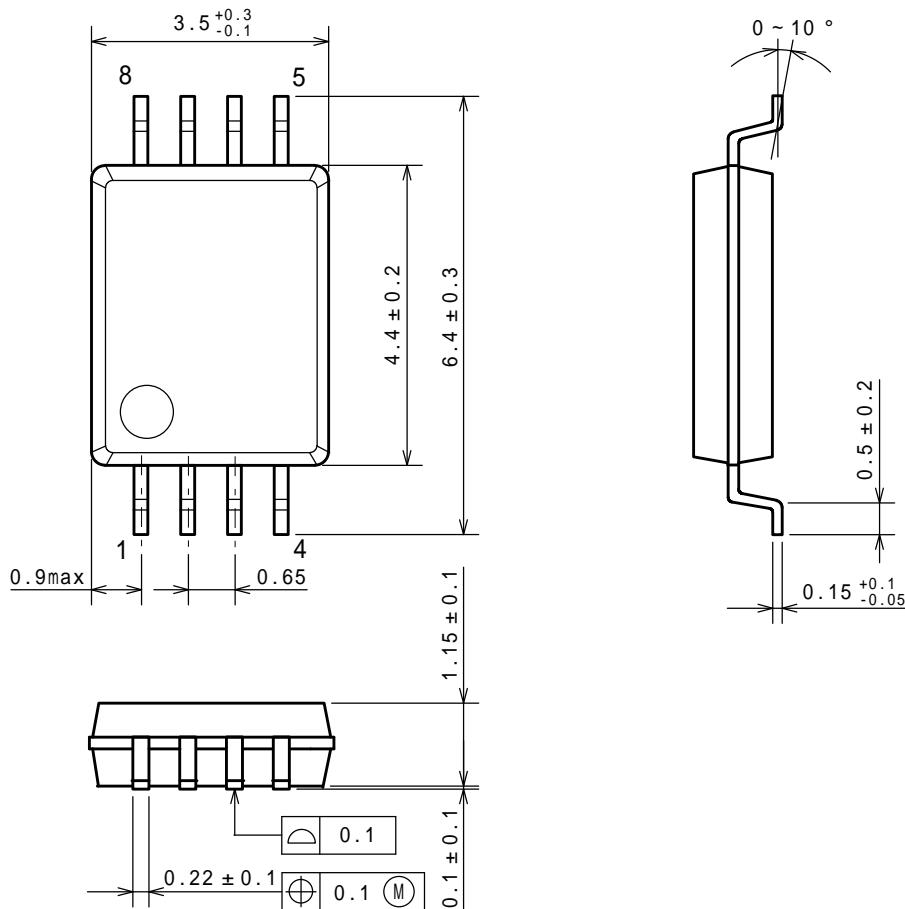
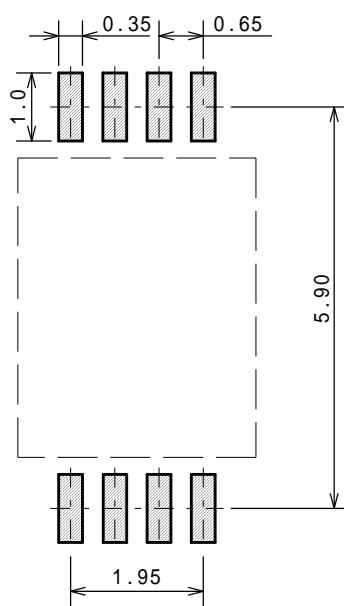
SOP8

Unit: mm

EXAMPLE OF SOLDER PADS DIMENSIONS

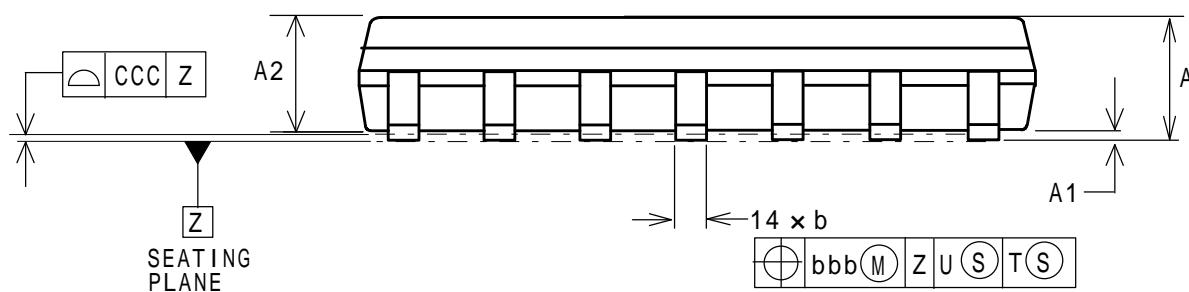
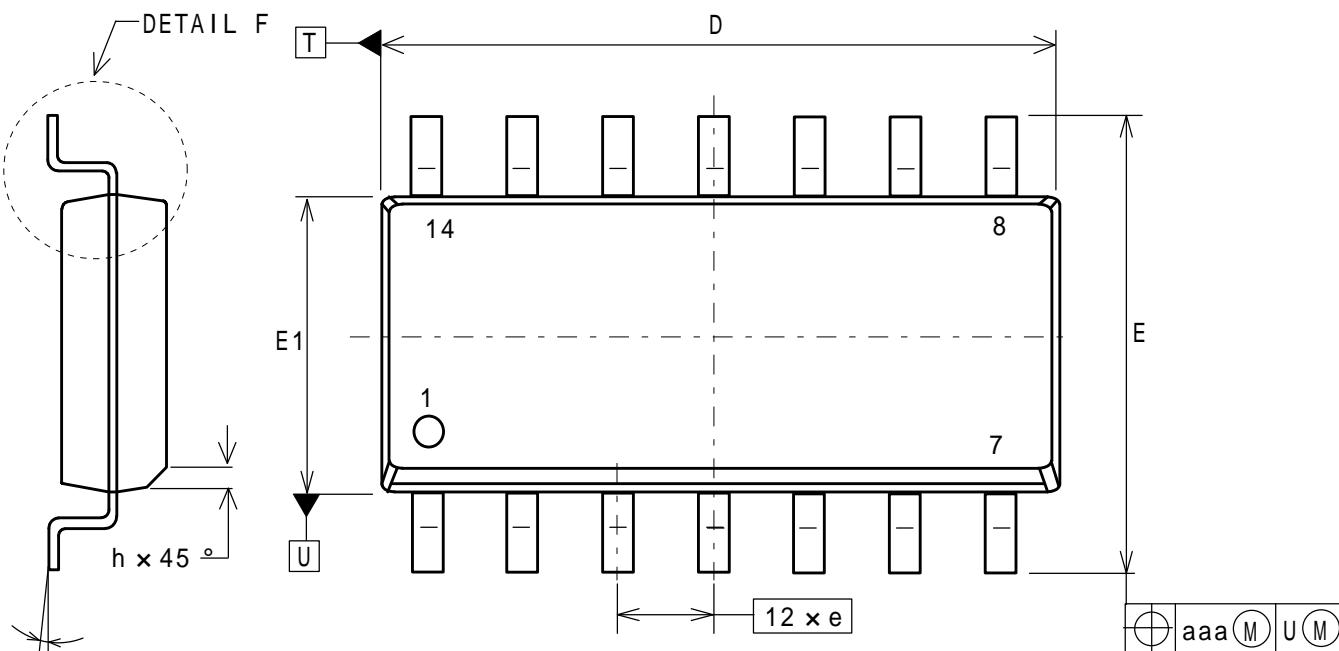
SSOP8

Unit: mm

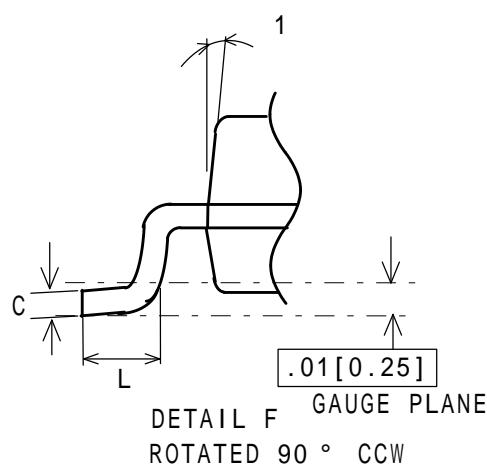
■ PACKAGE DIMENSIONS**■ EXAMPLE OF SOLDER PADS DIMENSIONS**

SOP14

Unit: mm

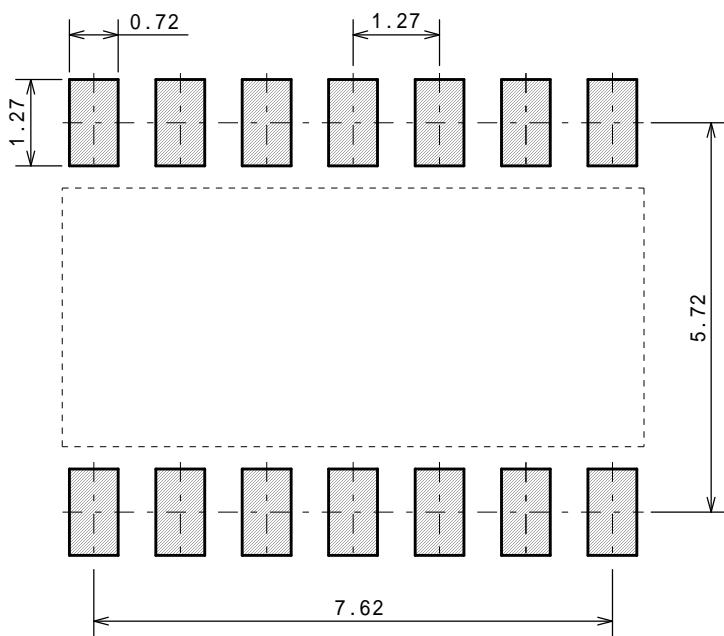
■ PACKAGE DIMENSIONS


DESCRIPTION	SYMBOL	INCH			MILLIMETER		
		MIN	NCM	MAX	MIN	NCM	MAX
TOTAL THICKNESS	A	.053		.069	1.35		1.75
STAND OFF	A1	.004		.010	0.10		0.25
MOLD THICKNESS	A2	.049		-	1.25		-
LEAD WIDTH	b	.013		.020	0.33		0.51
L/F THICKNESS	C	.007		.010	0.19		0.25
BODY SIZE	D	.337		.344	8.55		8.75
	E1	.150		.157	3.80		4.00
LEAD PITCH	E	.228		.244	5.80		6.20
	e	.050 BSC			1.27 BSC		
LEAD EDGE OFFSET	L	.016		.050	0.40		1.27
	h	.010		.020	0.25		0.50
	1	0 °		8 °	0 °		8 °
	aaa		.010		0.25		
LEAD OFFSET	bbb		.010		0.25		
COPLANARITY	CCC		.004		0.10		



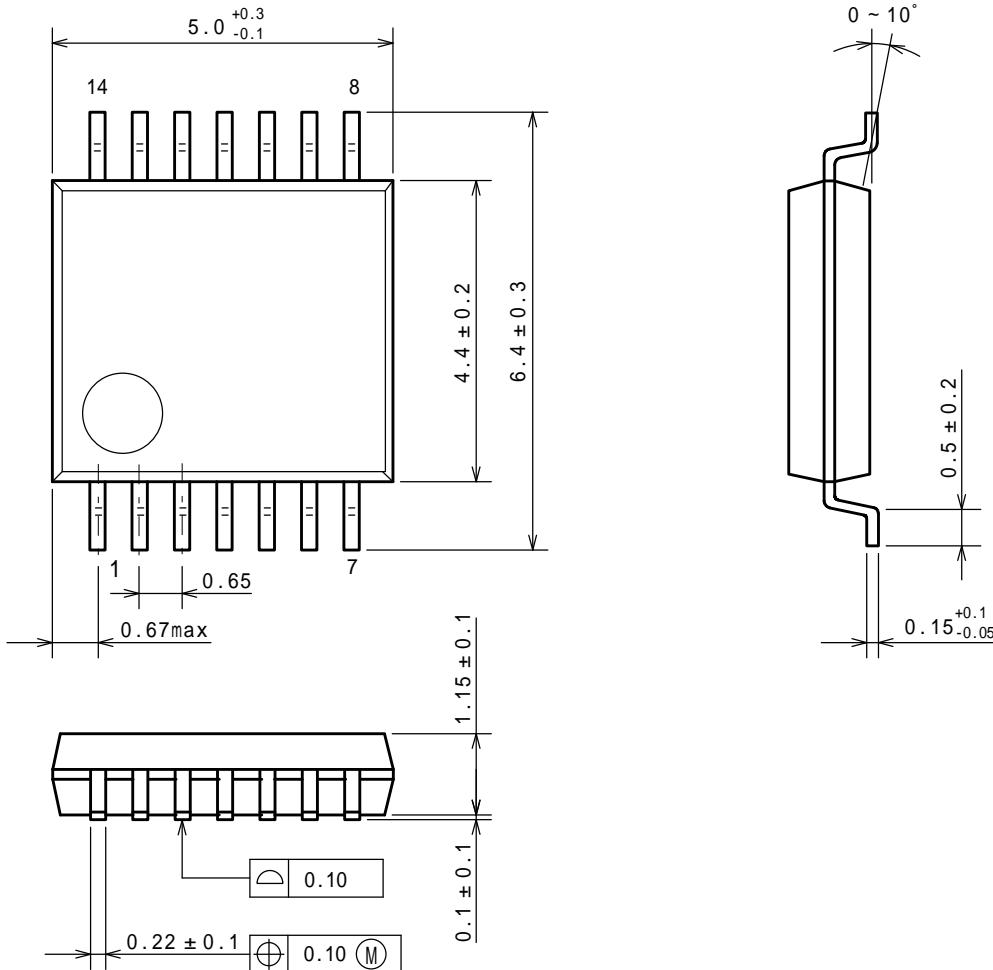
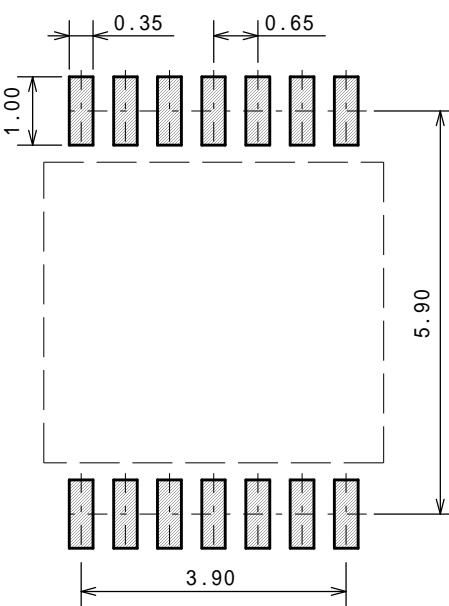
SOP14

Unit: mm

■EXAMPLE OF SOLDER PADS DIMENSIONS

SSOP14

Unit: mm

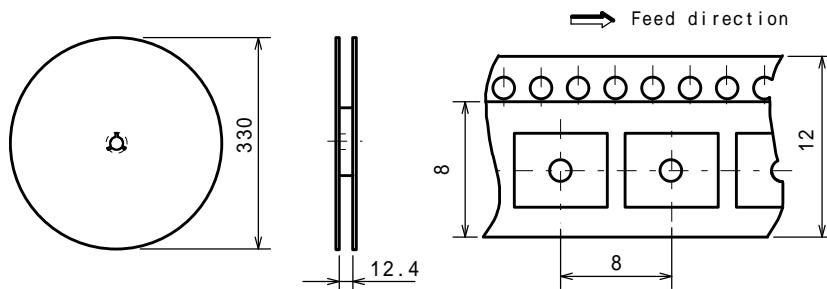
■ PACKAGE DIMENSIONS**■ EXAMPLE OF SOLDER PADS DIMENSIONS**

SOP8

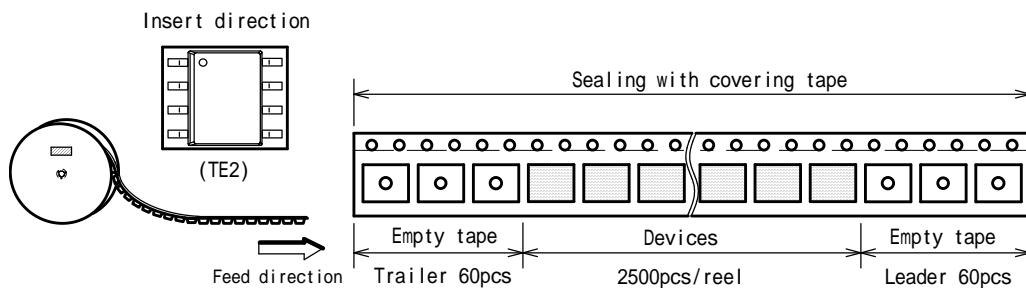
■ PACKING SPEC

Unit: mm

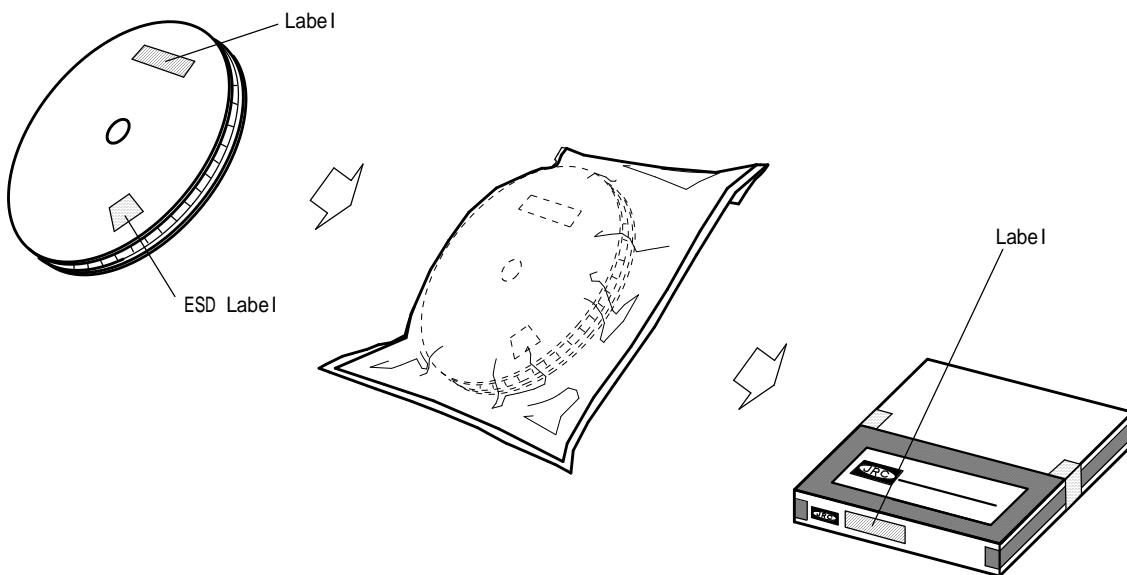
REEL DIMENSIONS / TAPING DIMENSIONS



TAPING STATE



PACKING STATE

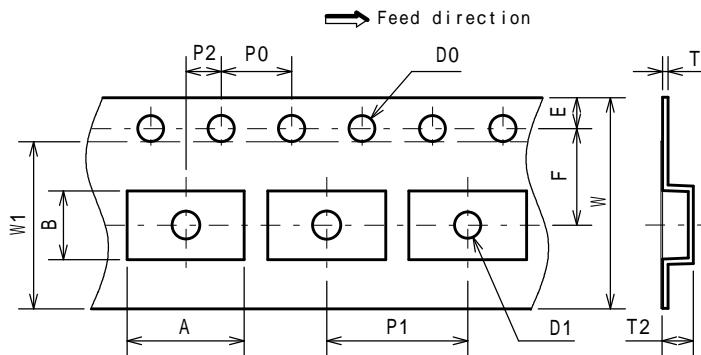


SSOP8

■ PACKING SPEC

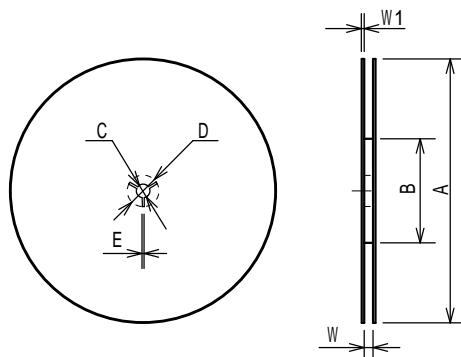
Unit: mm

TAPING DIMENSIONS



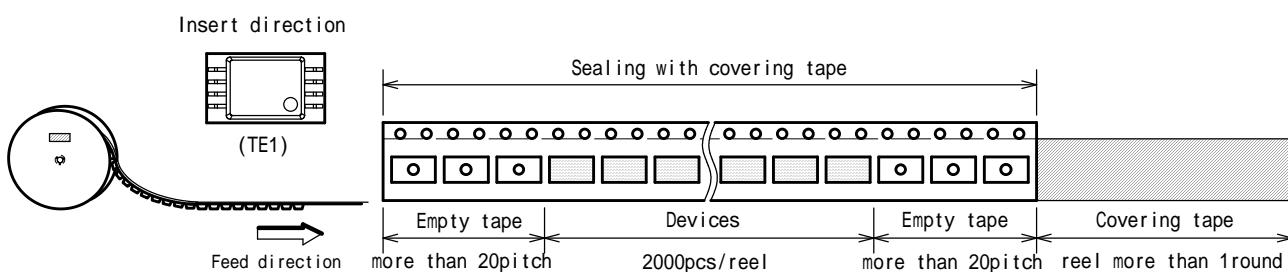
SYMBOL	DIMENSION	REMARKS
A	6.7	BOTTOM DIMENSION
B	3.9	BOTTOM DIMENSION
D0	1.55 ± 0.05	
D1	1.55 ± 0.1	
E	1.75 ± 0.1	
F	5.5 ± 0.05	
P0	4.0 ± 0.1	
P1	8.0 ± 0.1	
P2	2.0 ± 0.05	
T	0.3 ± 0.05	
T2	2.2	
W	12.0 ± 0.3	
W1	9.5	THICKNESS 0.1max

REEL DIMENSIONS

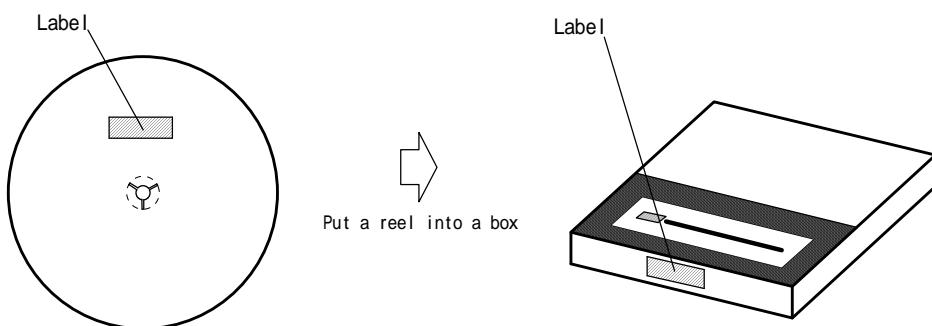


SYMBOL	DIMENSION
A	254 ± 2
B	100 ± 1
C	13 ± 0.2
D	21 ± 0.8
E	2 ± 0.5
W	13.5 ± 0.5
W1	2 ± 0.2

TAPING STATE



PACKING STATE

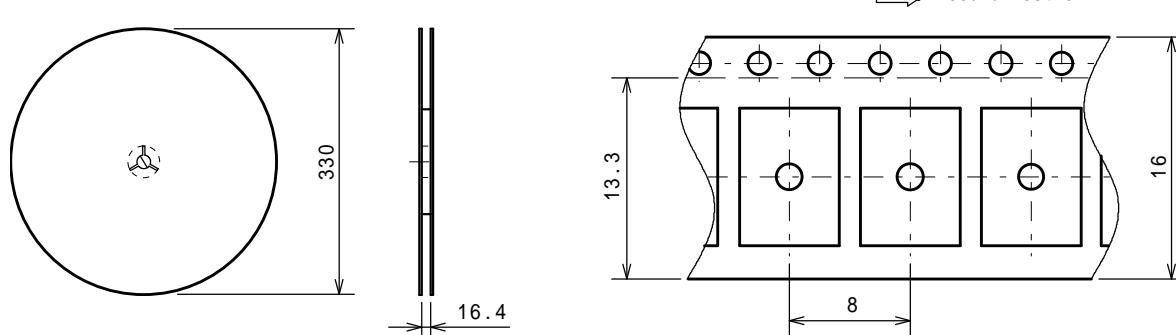


SOP14

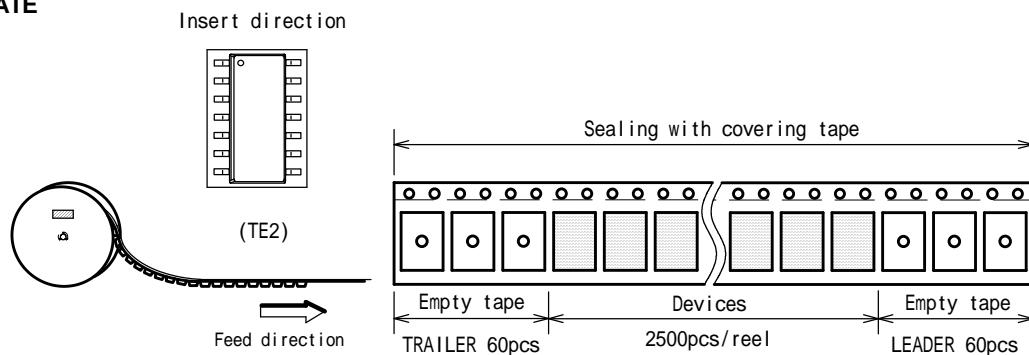
■ PACKING SPEC

Unit: mm

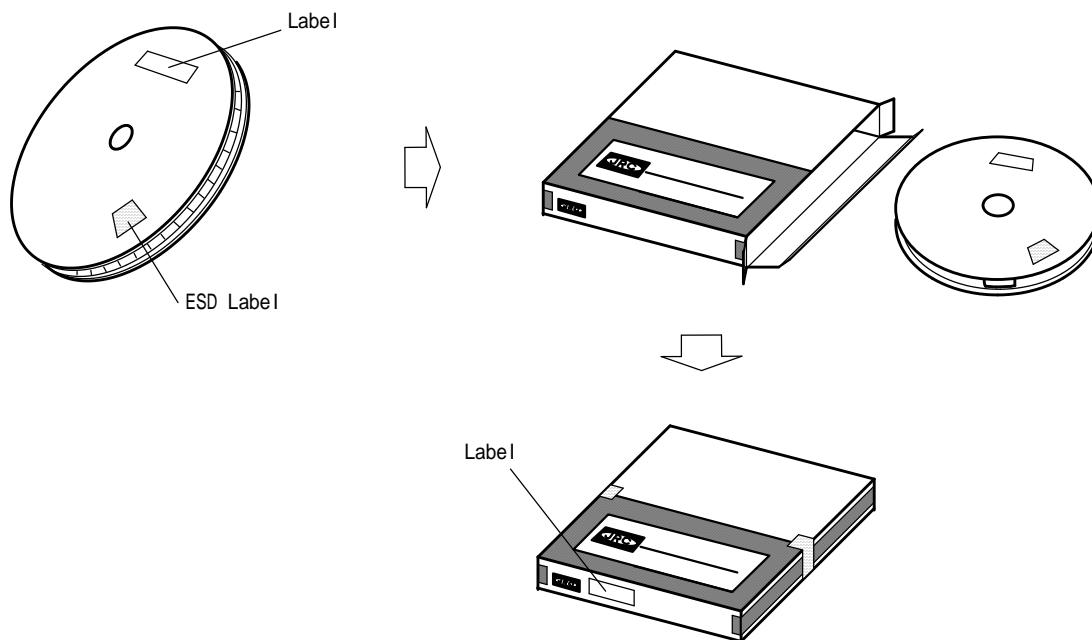
REEL DIMENSIONS / TAPING DIMENSIONS



TAPING STATE



PACKING STATE

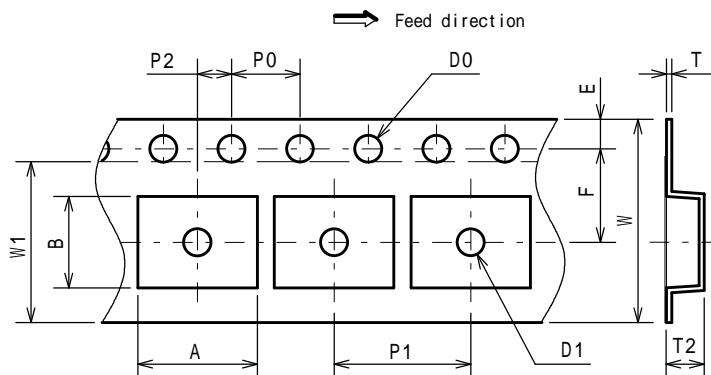


SSOP14

■ PACKING SPEC

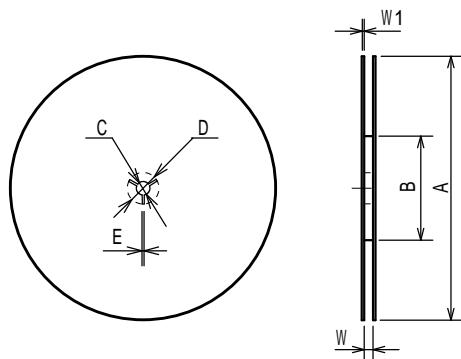
Unit: mm

TAPING DIMENSIONS



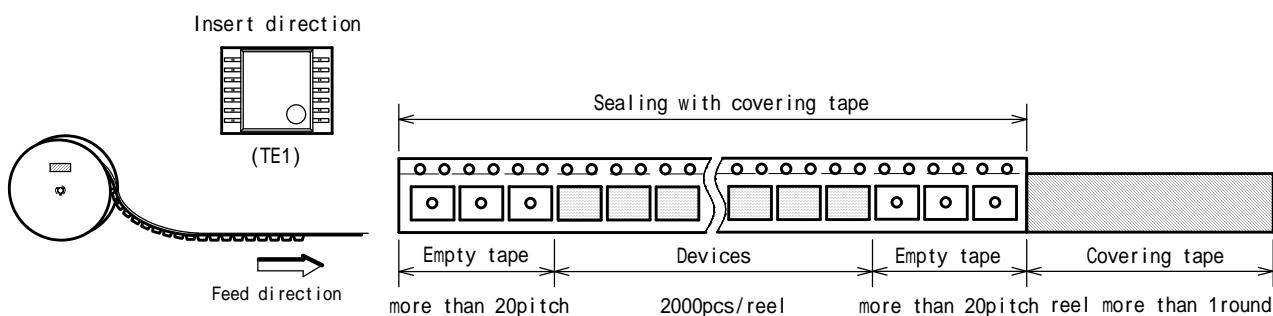
SYMBOL	DIMENSION	REMARKS
A	6.95	BOTTOM DIMENSION
B	5.4	BOTTOM DIMENSION
D0	1.55 ± 0.05	
D1	1.55 ± 0.1	
E	1.75 ± 0.1	
F	5.5 ± 0.05	
P0	4.0 ± 0.1	
P1	8.0 ± 0.1	
P2	2.0 ± 0.05	
T	0.3 ± 0.05	
T2	2.2	
W	12.0 ± 0.3	
W1	9.5	THICKNESS 0.1max

REEL DIMENSIONS

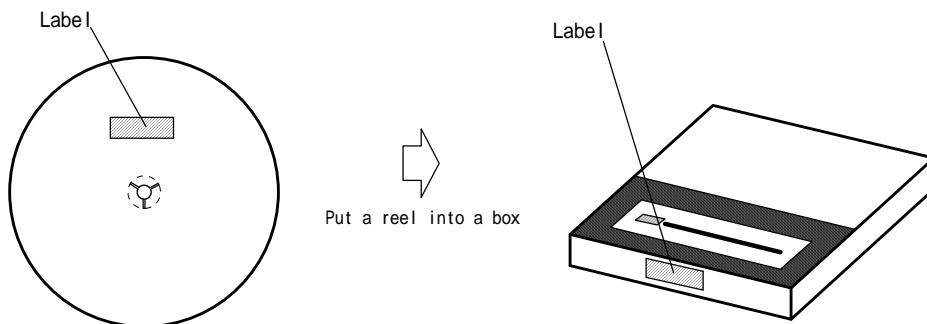


SYMBOL	DIMENSION
A	254 ± 2
B	100 ± 1
C	13 ± 0.2
D	21 ± 0.8
E	2 ± 0.5
W	13.5 ± 0.5
W1	2 ± 0.2

TAPING STATE

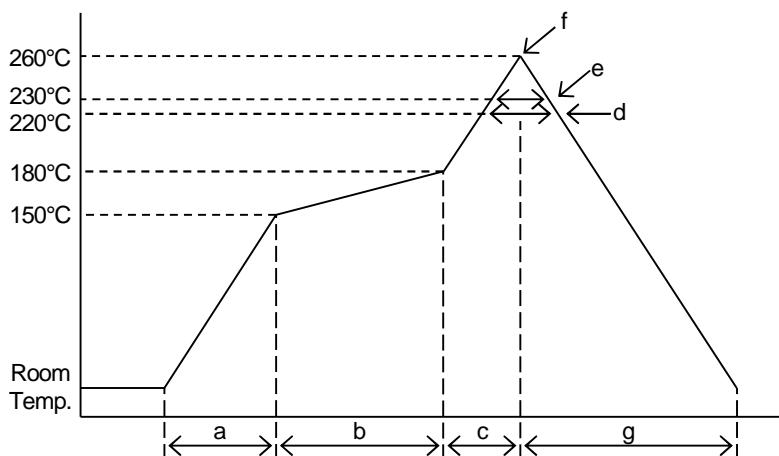


PACKING STATE



■ RECOMMENDED MOUNTING METHOD

INFRARED REFLOW SOLDERING PROFILE



a	Temperature ramping rate	1 to 4°C/s
b	Pre-heating temperature Pre-heating time	150 to 180°C 60 to 120s
c	Temperature ramp rate	1 to 4°C/s
d	220°C or higher time	shorter than 60s
e	230°C or higher time	shorter than 40s
f	Peak temperature	lower than 260°C
g	Temperature ramping rate	1 to 6°C/s

The temperature indicates at the surface of mold package.

■ REVISION HISTORY

DATE	REVISION	CHANGES
Feb.25, 2019	Ver.3.0	Data sheet format revision
Jun.6, 2019	Ver.3.1	Equivalent circuit revision
Nov.13, 2019	Ver.4.0	Extended operating temperature range
Mar.16, 2020	Ver.4.1	Added SSOP package.
Jul.16, 2020	Ver.5.0	NJM074CAV/084CV/084CAV Development completed



NJM072C/074C NJM072CA/074CA NJM082C/084C NJM082CA/084CA

[CAUTION]

1. NJR strives to produce reliable and high quality semiconductors. NJR's semiconductors are intended for specific applications and require proper maintenance and handling. To enhance the performance and service of NJR's semiconductors, the devices, machinery or equipment into which they are integrated should undergo preventative maintenance and inspection at regularly scheduled intervals. Failure to properly maintain equipment and machinery incorporating these products can result in catastrophic system failures
2. The specifications on this datasheet are only given for information without any guarantee as regards either mistakes or omissions. The application circuits in this datasheet are described only to show representative usages of the product and not intended for the guarantee or permission of any right including the industrial property rights.
All other trademarks mentioned herein are the property of their respective companies.
3. To ensure the highest levels of reliability, NJR products must always be properly handled.
The introduction of external contaminants (e.g. dust, oil or cosmetics) can result in failures of semiconductor products.
4. NJR offers a variety of semiconductor products intended for particular applications. It is important that you select the proper component for your intended application. You may contact NJR's Sale's Office if you are uncertain about the products listed in this datasheet.
5. Special care is required in designing devices, machinery or equipment which demand high levels of reliability. This is particularly important when designing critical components or systems whose failure can foreseeably result in situations that could adversely affect health or safety. In designing such critical devices, equipment or machinery, careful consideration should be given to amongst other things, their safety design, fail-safe design, back-up and redundancy systems, and diffusion design.
6. The products listed in this datasheet may not be appropriate for use in certain equipment where reliability is critical or where the products may be subjected to extreme conditions. You should consult our sales office before using the products in any of the following types of equipment.
 - Aerospace Equipment
 - Equipment Used in the Deep Sea
 - Power Generator Control Equipment (Nuclear, steam, hydraulic, etc.)
 - Life Maintenance Medical Equipment
 - Fire Alarms / Intruder Detectors
 - Vehicle Control Equipment (Airplane, railroad, ship, etc.)
 - Various Safety Devices
7. NJR's products have been designed and tested to function within controlled environmental conditions. Do not use products under conditions that deviate from methods or applications specified in this datasheet. Failure to employ the products in the proper applications can lead to deterioration, destruction or failure of the products. NJR shall not be responsible for any bodily injury, fires or accident, property damage or any consequential damages resulting from misuse or misapplication of the products. The products are sold without warranty of any kind, either express or implied, including but not limited to any implied warranty of merchantability or fitness for a particular purpose.
8. Warning for handling Gallium and Arsenic (GaAs) Products (Applying to GaAs MMIC, Photo Reflector). These products use Gallium (Ga) and Arsenic (As) which are specified as poisonous chemicals by law. For the prevention of a hazard, do not burn, destroy, or process chemically to make them as gas or power. When the product is disposed of, please follow the related regulation and do not mix this with general industrial waste or household waste.
9. The product specifications and descriptions listed in this datasheet are subject to change at any time, without notice.

